SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995

10**U**T

3 20UT

- Meets or Exceeds the Requirements of ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B and ITU Recommendations V.10 and V.11
- Operates From Single 5-V Power Supply
- Wide Common-Mode Voltage Range
- High Input Impedance
- TTL-Compatible Outputs
- High-Speed Schottky Circuitry
- 8-Pin Dual-in-Line and Small-Outline Packages
- Designed to Be Interchangeable With National DS9637A

## (TOP VIEW) V<sub>CC</sub> 1 8 11N+ 10UT 2 7 11N-20UT 3 6 21N+ GND 4 5 21N-

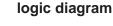
uA9637AC ... D OR P PACKAGE

#### description

The uA9637AC is a dual differential line receiver designed to meet ANSI Standards EIA/TIA-422-B and EIA/TIA-423-B and ITU Recommendations V.10 and V.11. The line receiver utilizes Schottky circuitry and has TTL-compatible outputs. The inputs are compatible with either a single-ended or a differential-line system. This device operates from a single 5-V power supply and is supplied in an 8-pin dual-in-line package or small-outline package.

The uA9637AC is characterized for operation from 0°C to 70°C.

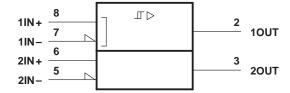
#### logic symbol<sup>†</sup>

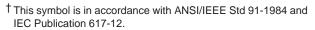


1IN 4

2IN+

21N







Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

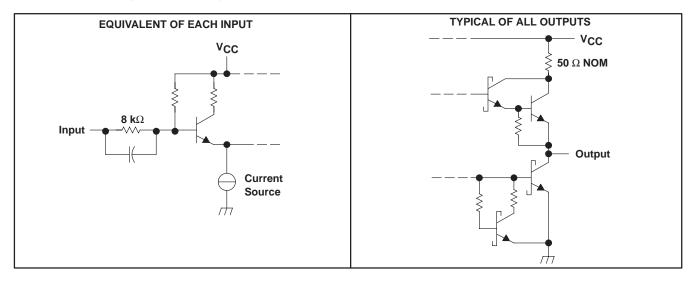
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1995, Texas Instruments Incorporated

SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995

#### schematics of inputs and outputs



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub> (see Note 1)	
Differential input voltage, V <sub>ID</sub> (see Note 2)	
Output voltage range, V <sub>O</sub> (see Note 1)	0.5 V to 5.5 V
Low-level output current, IOL	50 mA
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	0°C to 70°C
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltage, are with respect to the network ground terminal.
  - 2. Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

#### DISSIPATION RATING TABLE

PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	OPERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW	—
Р	1000 mW	8.0 mW/°C	640 mW	—



#### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
Common-mode input voltage, V <sub>IC</sub>			±7	V
Operating free-air temperature, TA	0		70	°C

# electrical characteristics over recommended ranges of supply voltage, common-mode input voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER	TEST CO	TEST CONDITIONS				UNIT
\/ı <del>_</del>	Positive-going input threshold voltage	See Note 3				0.2	V
VIT+	Positive-going input threshold voltage	See Note 5				0.4	v
V		Can Nata D		-0.2			V
$V_{IT-}$	Negative-going input threshold voltage	See Note 3		-0.4‡			v
V <sub>hys</sub>	Hysteresis voltage (V <sub>IT+</sub> -V <sub>IT-</sub> )				70		mV
VOH	High-level output voltage	V <sub>ID</sub> = 0.2 V,	$I_{O} = -1 \text{ mA}$	2.5	3.5		V
VOL	Low-level output voltage	$V_{ID} = -0.2 V,$	l <sub>O</sub> = 20 mA		0.35	0.5	V
1.	Input current	$V_{CC} = 0$ to 5.5 V,	V <sub>I</sub> = 10 V		1.1	3.25	mA
1	input current	See Note 4	$V_{I} = -10 V$		-1.6	-3.25	ША
IOS	Short-circuit output current§	$V_{O} = 0,$	$V_{ID} = 0.2 V$	-40	-75	-100	mA
ICC	Supply current	V <sub>ID</sub> = -0.5 V,	No load		35	50	mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>‡</sup> The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for threshold levels only.

§ Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.

NOTES: 3. The expanded threshold parameter is tested with a 500- $\Omega$  resistor in series with each input.

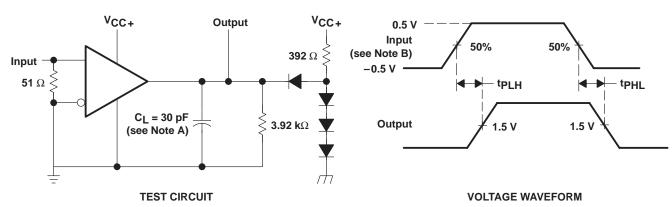
4. The input not under test is grounded.

## switching characteristics, V\_{CC} = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<sup>t</sup> PLH	Propagation delay time, low- to high-level output			15	25	ns
<sup>t</sup> PHL	Propagation delay time, high- to low-level output	$C_{L} = 30 \text{ pF}$ , See Figure 1		13	25	ns



SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995

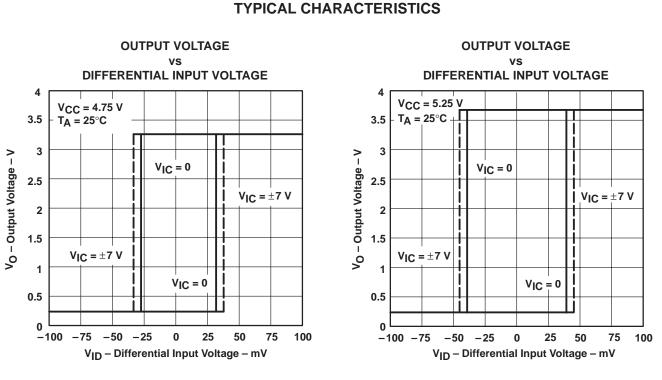


#### PARAMETER MEASUREMENT INFORMATION

NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

B. The input pulse is supplied by a generator having the following characteristics:  $t_f \le 5$  ns,  $t_f \le 5$  ns,  $PRR \le 5$  MHz, duty cycle = 50%.

Figure 1. Test Circuit and Voltage Waveform

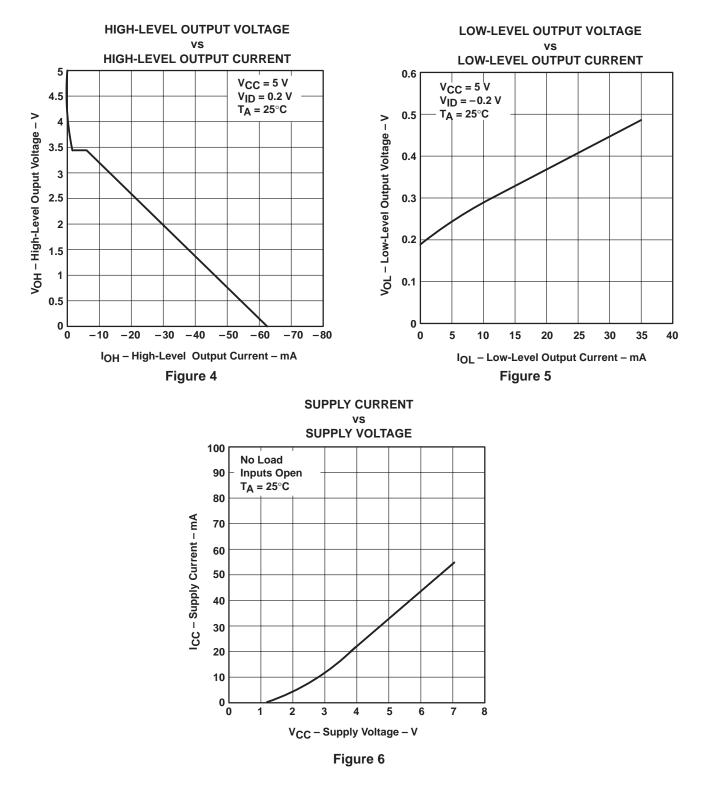








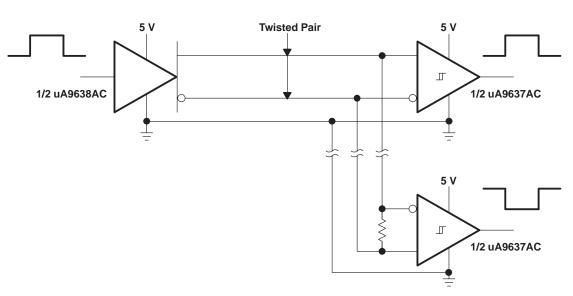
SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995



#### **TYPICAL CHARACTERISTICS**



SLLS111B - SEPTEMBER 1980 - REVISED MAY 1995



**APPLICATION INFORMATION** 

## Figure 7. EIA/TIA-422-B System Applications



V IEXAS NSTRUMENTS www.ti.com

#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
UA9637ACD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
UA9637ACJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
UA9637ACP	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
UA9637ACPE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
UA9637ACPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UA9637ACPSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
UA9637ACPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

# PACKAGE OPTION ADDENDUM



4-Jun-2007

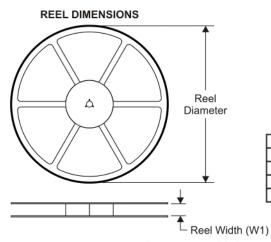
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

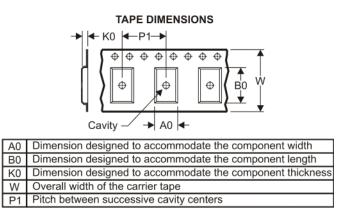
# PACKAGE MATERIALS INFORMATION

www.ti.com

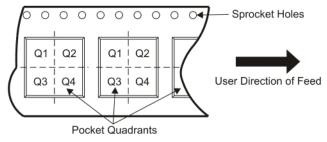
Texas Instruments

### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Package	Pine
*All dimensions are nominal			

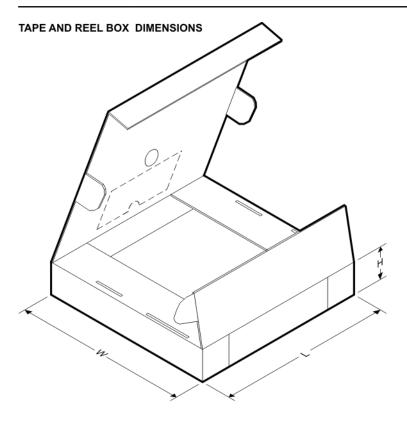
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UA9637ACDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

TEXAS INSTRUMENTS

www.ti.com

# PACKAGE MATERIALS INFORMATION

29-Jul-2011



\*All dimensions are nominal

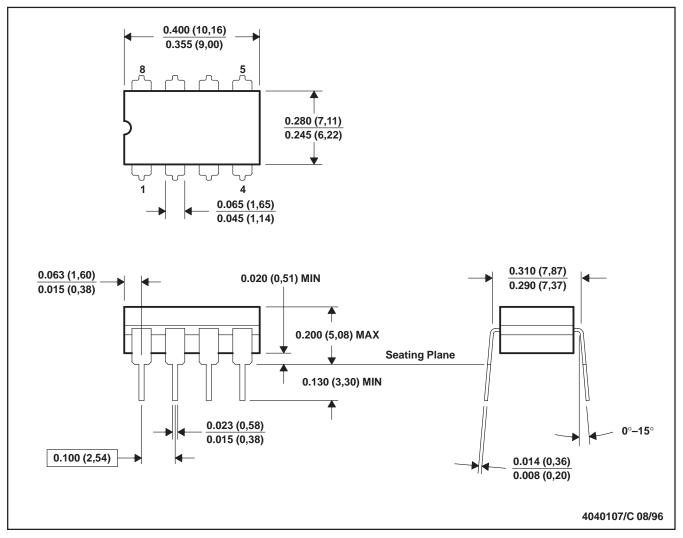
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UA9637ACDR	SOIC	D	8	2500	340.5	338.1	20.6

## **MECHANICAL DATA**

MCER001A - JANUARY 1995 - REVISED JANUARY 1997



#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8



P(R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE

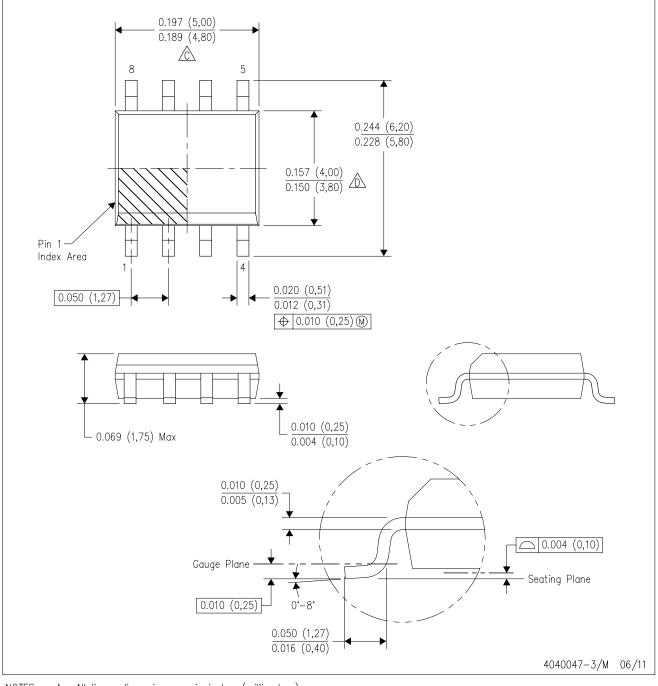


- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE

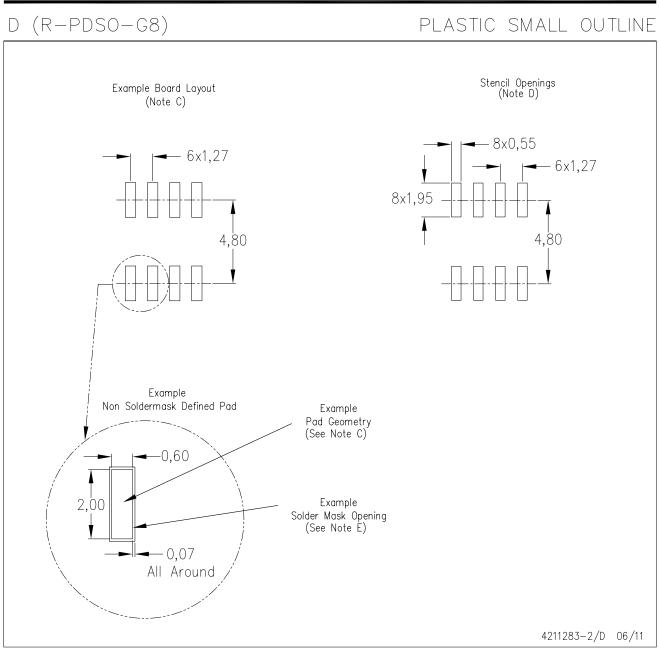


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



## LAND PATTERN DATA



NOTES: A. All linear dimensions are in millimeters.

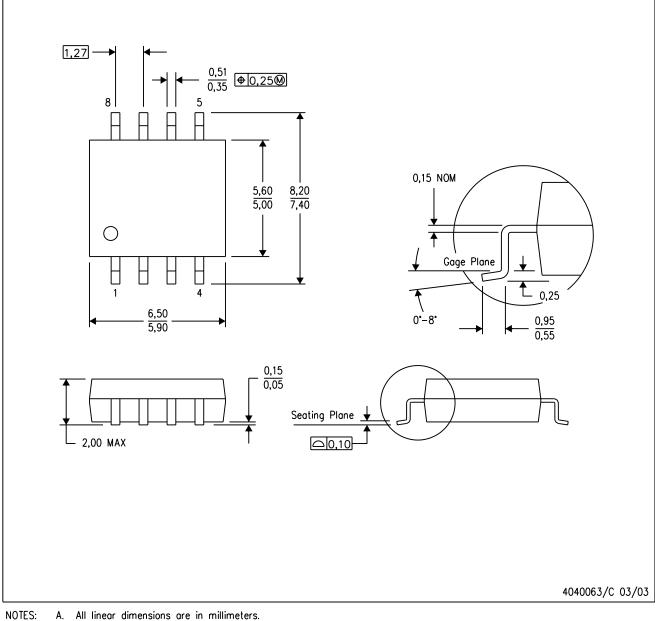
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

## PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Audio	www.ti.com/audio	Communications and Telecom	www.ti.com/communications
Amplifiers	amplifier.ti.com	Computers and Peripherals	www.ti.com/computers
Data Converters	dataconverter.ti.com	Consumer Electronics	www.ti.com/consumer-apps
DLP® Products	www.dlp.com	Energy and Lighting	www.ti.com/energy
DSP	dsp.ti.com	Industrial	www.ti.com/industrial
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Security	www.ti.com/security
Logic	logic.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Power Mgmt	power.ti.com	Transportation and Automotive	www.ti.com/automotive
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com	Wireless	www.ti.com/wireless-apps
RF/IF and ZigBee® Solutions	www.ti.com/lprf		

**TI E2E Community Home Page** 

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2011, Texas Instruments Incorporated